

ABSTRACT

[0037] A semiconductor die carrier includes a radiation shielding base having a radiation shielding integrated base flange extending orthogonally from an upper surface of the base, the integrated base flange having an upper surface. A substrate is disposed on the radiation shielding base and around the integrated base flange, the substrate has an uppermost tier with an upper surface that is not higher than the upper surface of said integrated base flange. A radiation shielding seal lid has a radiation shielding integrated seal lid flange, the radiation shielding integrated seal lid flange has a lower surface disposed on the upper surface of the uppermost tier of the substrate.

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